SN54AHCT158, SN74AHCT158 QUADRUPLE 2-LINE TO 1-LINE DATA SELECTORS/MULTIPLEXERS

SCLS348J - MAY 1996 - REVISED JULY 2003

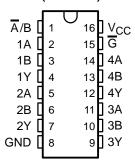
- Inputs Are TTL-Voltage Compatible
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

description/ordering information

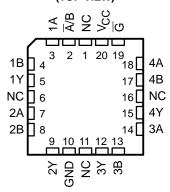
These quadruple 2-line to 1-line data selectors/multiplexers are designed for 4.5-V to 5.5-V V_{CC} operation.

The 'AHCT158 devices feature a common strobe (\overline{G}) input. When the strobe is high, all outputs are high. When the strobe is low, a 4-bit word is selected from one of two sources and is routed to the four outputs. The devices provide inverted data.

SN54AHCT158 . . . J OR W PACKAGE SN74AHCT158 . . . D, DB, DGV, N, NS, OR PW PACKAGE (TOP VIEW)



SN54AHCT158...FK PACKAGE (TOP VIEW)



NC - No internal connection

ORDERING INFORMATION

TA	PACKA	GE [†]	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – N	Tube	SN74AHCT158N	SN74AHCT158N
	SOIC - D	Tube	SN74AHCT158D	AHCT158
	3010-15	Tape and reel	SN74AHCT158DR	Anonio
–40°C to 85°C	SOP – NS	S Tape and reel SN74AHCT158NSR		AHCT158
40 0 10 03 0	SSOP – DB	Tape and reel	SN74AHCT158DBR	HB158
	TSSOP – PW	Tube	SN74AHCT158PW	HB158
	1330F = FW	Tape and reel	SN74AHCT158PWR	TID130
	TVSOP – DGV	Tape and reel	SN74AHCT158DGVR	HB158
	CDIP – J	Tube	SNJ54AHCT158J	SNJ54AHCT158J
–55°C to 125°C	CFP – W	Tube	SNJ54AHCT158W	SNJ54AHCT158W
	LCCC – FK	Tube	SNJ54AHCT158K	SNJ54AHCT158FK

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

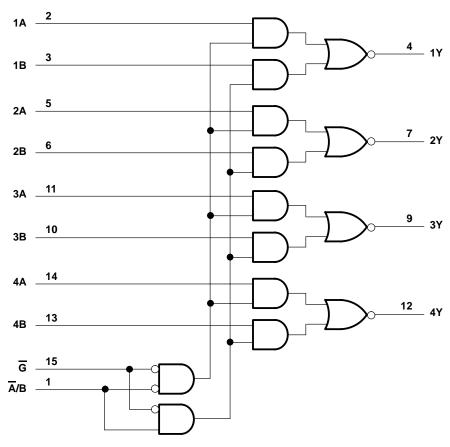


SCLS348J - MAY 1996 - REVISED JULY 2003

FUNCTION TABLE (each data selector/multiplexer)

	INPL	JTS		OUTPUT
G	Ā/B	Α	В	Y
Н	Х	Χ	Х	Н
L	L	L	X	Н
L	L	Н	X	L
L	Н	Χ	L	Н
L	Н	Χ	Н	L

logic diagram (positive logic)



Pin numbers shown are for the D, DB, DGV, J, N, NS, PW, and W packages.

SN54AHCT158, SN74AHCT158 QUADRUPLE 2-LINE TO 1-LINE DATA SELECTORS/MULTIPLEXERS

SCLS348J - MAY 1996 - REVISED JULY 2003

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}		–0.5 V to 7 V
Input voltage range, V _I (see Note 1)		–0.5 V to 7 V
Output voltage range, VO (see Note 1)		$0.5 V$ to $V_{CC} + 0.5 V$
Input clamp current, I_{IK} ($V_I < 0$)		–20 mA
Output clamp current, IOK (VO < 0 or VO > VCO	c)	±20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})		±25 mA
Continuous current through V _{CC} or GND		±50 mA
Package thermal impedance, θ_{JA} (see Note 2):	D package	73°C/W
•	DB package	82°C/W
	DGV package	120°C/W
	N package	67°C/W
	NS package	64°C/W
	PW package	108°C/W
Storage temperature range, T _{stg}		–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

		SN54AHCT158		SN74AH	CT158	UNIT
		MIN	MAX	MIN	MAX	UNIT
VCC	Supply voltage	4.5	5.5	4.5	5.5	V
VIH	High-level input voltage	2	7	2		V
VIL	Low-level input voltage		0.8		0.8	V
٧ _I	Input voltage	0	5.5	0	5.5	V
Vo	Output voltage	0	Vcc	0	VCC	V
IOH	High-level output current	27/	-8		-8	mA
l _{OL}	Low-level output current	70 ₂	8		8	mA
Δt/Δν	Input transition rise or fall time	Q	20		20	ns/V
TA	Operating free-air temperature	- 55	125	-40	85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

SN54AHCT158, SN74AHCT158 QUADRUPLE 2-LINE TO 1-LINE DATA SELECTORS/MULTIPLEXERS

SCLS348J - MAY 1996 - REVISED JULY 2003

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	vcc	T _A = 25°C			SN54AHCT158		SN74AHCT158		UNIT	
PARAMETER	TEST CONDITIONS		MIN	TYP	MAX	MIN	MAX	MIN	MAX	ONIT	
V	I _{OH} = -50 μA		4.4	4.5		4.4		4.4		٧	
VOH	I _{OH} = -8 mA	4.5 V	3.94			3.8	, la	3.8		V	
V	I _{OL} = 50 μA	4.5 V			0.1		0.1		0.1	V	
VOL	I _{OL} = 8 mA	4.5 V			0.36		0.44		0.44	l v	
lį	V _I = 5.5 V or GND	0 V to 5.5 V			±0.1	<i>\(\frac{1}{2} \)</i>	±1*		±1	μΑ	
Icc	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			2	370	20		20	μΑ	
ΔI _{CC} †	One input at 3.4 V, Other inputs at V _{CC} or GND	5.5 V			1.35	04'0	1.5		1.5	mA	
C _i	V _I = V _{CC} or GND	5 V		2	10				10	pF	

^{*} On products compliant to MIL-PRF-38535, this parameter is not production tested at $V_{CC} = 0 \text{ V}$.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

00	•		, ,	•	,						
PARAMETER	FROM	то	LOAD	T	չ = 25°C	;	SN54AH	CT158	SN74AH	CT158	UNIT
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
^t PLH	A or B	Y	C: 15 pF		4.1**	6.4**	1**	7.5**	1	7.5	
^t PHL	AOIB	Ť	C _L = 15 pF		4.1**	6.4**	1**	7.5**	1	7.5	ns
^t PLH	Ā/B	Y	C _L = 15 pF		5.3**	8.1**	1**	9.5**	1	9.5	no
^t PHL	A/B	l ¹			5.3**	8.1**	1**	9.5**	1	9.5	9.5 ns
^t PLH	G	Y	C _L = 15 pF		5.6**	8.6**	1**	10**	1	10	
^t PHL]	l t		OL = 13 pr		5.6**	8.6**	1**	10**	1	10
^t PLH	A or B	Y	C 50 pF		5.6	8.7	1,0	10.8	1	9.8	20
^t PHL	A or B	Y	$C_L = 50 \text{ pF}$		5.6	8.7	3	10.8	1	9.8	ns
^t PLH		Y	C 50 pF		6.8	10.4	Q ₁	13.2	1	12	no
t _{PLH}] A/B	f	C _L = 50 pF		6.8	10.4	0 1	13.2	1	12	ns
^t PLH	G	Y	C: - 50 pF		7.1	11	1	13.5	1	12	20
^t PHL]	f	C _L = 50 pF		7.1	11	1	13.5	1	12	ns

^{**} On products compliant to MIL-PRF-38535, this parameter is not production tested.

noise characteristics $V_{CC} = 5 \text{ V}$, $C_L = 50 \text{ pF}$, $T_A = 25^{\circ}\text{C}$ (see Note 4)

	PARAMETER	SN7	UNIT			
	PARAMETER	MIN	TYP	MAX	CIVIT	
V _{OL(P)}	Quiet output, maximum dynamic V _{OL}			0.8	V	
V _{OL(V)}	Quiet output, minimum dynamic V _{OL}			-0.8	V	
VOH(V)	Quiet output, minimum dynamic VOH		4.8		V	
V _{IH(D)}	High-level dynamic input voltage	2			V	
V _{IL(D)}	Low-level dynamic input voltage			0.8	V	

NOTE 4: Characteristics are for surface-mount packages only.



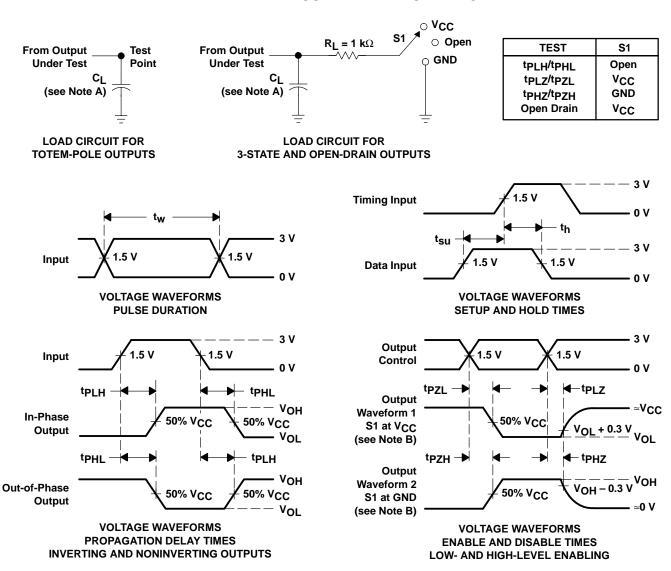
[†] This is the increase in supply current for each input at one of the specified TTL voltage levels rather than 0 V or VCC.

SCLS348J - MAY 1996 - REVISED JULY 2003

operating characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$

	PARAMETER	TEST CO	SNOITIONS	TYP	UNIT
C _{pd}	Power dissipation capacitance	No load,	f = 1 MHz	11	pF

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O = 50~\Omega$, $t_f \leq$ 3 ns, $t_f \leq$ 3 ns.
- D. The outputs are measured one at a time with one input transition per measurement.
- E. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms



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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
							(6)				
SN74AHCT158D	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AHCT158	Samples
SN74AHCT158PW	ACTIVE	TSSOP	PW	16	90	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HB158	Samples
SN74AHCT158PWR	ACTIVE	TSSOP	PW	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HB158	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE MATERIALS INFORMATION

www.ti.com 9-Aug-2022

TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

	Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
j	SN74AHCT158PWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

PACKAGE MATERIALS INFORMATION

www.ti.com 9-Aug-2022



*All dimensions are nominal

Ì	Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)	
ı	SN74AHCT158PWR	TSSOP	PW	16	2000	356.0	356.0	35.0	

PACKAGE MATERIALS INFORMATION

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TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN74AHCT158D	D	SOIC	16	40	507	8	3940	4.32
SN74AHCT158PW	PW	TSSOP	16	90	530	10.2	3600	3.5

D (R-PDS0-G16)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.





SMALL OUTLINE PACKAGE



NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
- 5. Reference JEDEC registration MO-153.



SMALL OUTLINE PACKAGE



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE PACKAGE



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



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